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# N-Channel 60 V (D-S) Super Junction Power MOSFET

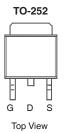
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>			
60	0.0023 at V <sub>GS</sub> = 10 V	120			
60	0.0049 at V <sub>GS</sub> = 4.5 V	75			

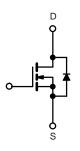
#### **FEATURES**

- DT-Trench Power MOSFET
- 100 %  $R_g$  and UIS Tested



RoHS COMPLIANT





N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	$V_{GS}$	± 20	V			
Continuous Drain Current (T <sub>.1</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	L	120			
Continuous Drain Current (1 <sub>J</sub> = 175 °C) <sup>2</sup>	T <sub>C</sub> = 100 °C	- I <sub>D</sub>	85 <sup>a</sup>			
Pulsed Drain Current	I <sub>DM</sub>	480	А			
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	110 <sup>a</sup>				
Avalanche Current	I <sub>AS</sub>	120				
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	288	mJ		
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	205	W		
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	' D	5.6 <sup>b</sup>	V		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maniana lanatian ta Arabianti	t ≤ 10 sec	D	9	15		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	R <sub>thJA</sub>	15	45	°C/W	
Maximum Junction-to-Case	•	R <sub>thJC</sub>	0.95	1.5		

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t \le 10 \text{ s}$ .





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<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	=	3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V	1		1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
		V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	150			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0023	0.0033		
D : 0	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> =20 A, T <sub>J</sub> = 125 °C		0.0032	0.0040		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> =15 A, T <sub>J</sub> = 175 °C		0.0039	0.0048	Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.0049	0.0062		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	$V_{DS} = 48 \text{ V}, I_{D} = 20 \text{ A}$		165		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			10100			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 48 \text{ V}, f = 1 \text{ MHz}$		1588		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			157			
Total Gate Charge <sup>c</sup>	$Q_g$			74	89		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 48 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		15		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			19			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			18			
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 48 \text{ V}, R_{L} = 0.6 \Omega$		32		ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		66			
Fall Time <sup>c</sup>	t <sub>f</sub>			13			
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				480	Α	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V			1.25	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		73		ns	

#### Notes:

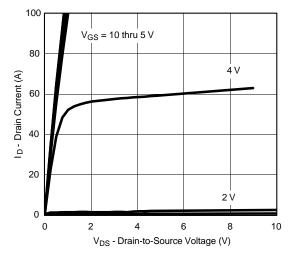
- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

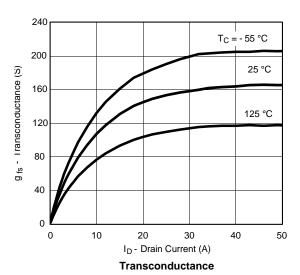


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### TYPICAL CHARACTERISTICS (25 °C unless noted)



### **Output Characteristics**



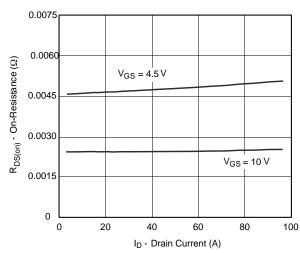
12000 10500  $C_{\text{iss}}$ 9000 C - Capacitance (pF) 7500 6000 4500 3000 Coss 1500 0 0 10 30 50 60 V<sub>DS</sub> - Drain-to-Source Voltage (V)

Capacitance

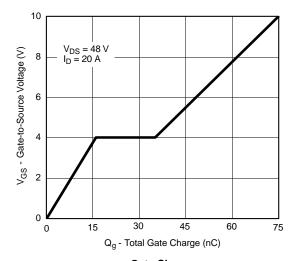
100 80 T<sub>C</sub> = 125 °C -55 °C 20 0 0 0.8 1.6 2.4 3.2 4.0

**Transfer Characteristics** 

V<sub>GS</sub> - Gate-to-Source Voltage (V)



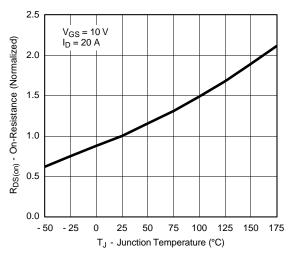
On-Resistance vs. Drain Current



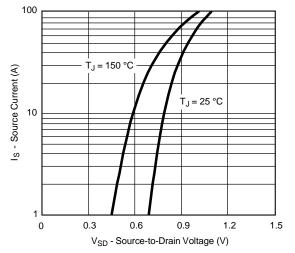
**Gate Charge** 



# TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

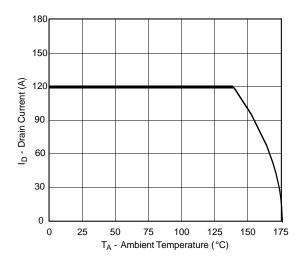


Source-Drain Diode Forward Voltage



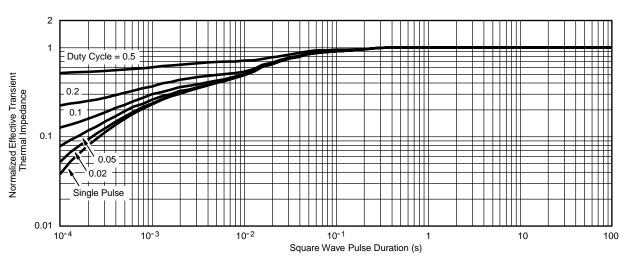


#### **THERMAL RATINGS**



1000 Limited by R<sub>DS(on)</sub>\* 100 10 µs 100 µs I<sub>D</sub> - Drain Current (A) 10 1 ms 10 ms 100 ms DC T<sub>C</sub> = 25 °C Single Pulse 0.1 0.01 100  $V_{DS} - Drain-to-Source \ Voltage \ (V) \\ ^*V_{GS} > minimum \ V_{GS} \ at \ which \ R_{DS(on)} \ is \ specified$ Safe Operating Area

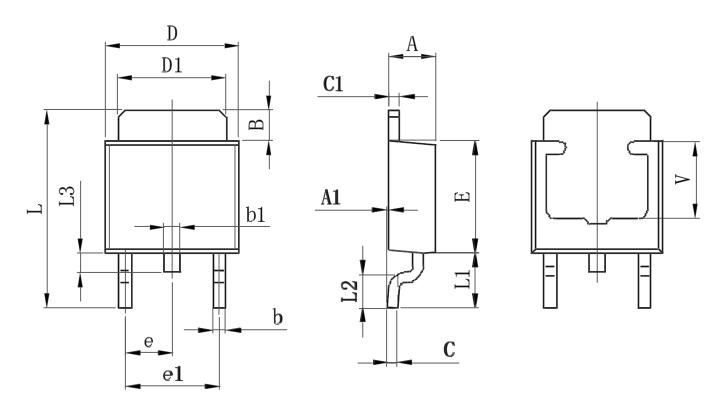
Maximum Drain Current vs. Ambient Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



Din-Tek SEMICONDUCTOR

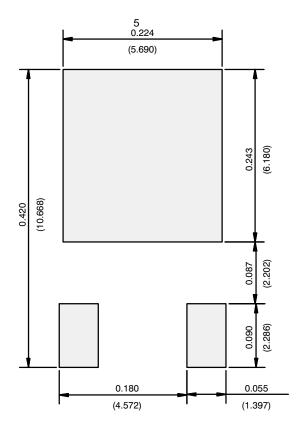


Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300	TYP.	0.091 TYP.		
e1	4.500	4.700	0.177	0.185	
L	9.500	9.900	0.374	0.390	
L1	2.550	2.900	0.100	0.114	
L2	1.400	1.780	0.055	0.070	
L3	0.600	0.900	0.024	0.035	
V	3.800	REF.	0.150	REF.	





## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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